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To: _____

PRELIMINARY SPECIFICATIONS

Product Type 1/3-type Color CCD Area Sensor with 470k Pixels for PAL

LZ2363B

Model No. _____

※This specifications contains 18 pages including the cover and appendix.
If you have any objections, please contact us before issuing purchasing order.

CUSTOMERS ACCEPTANCE

DATE: _____

BY: _____

PRESENTED

BY: K. Misawa
K. MISAWA
Dept. General Manager

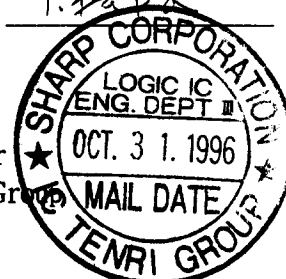
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SHARP CORPORATION



CONTENTS

1. GENERAL DESCRIPTION	2
2. ARRANGEMENT OF PIXELS AND COLOR FILTERS	3
3. PIN IDENTIFICATION	4
4. ABSOLUTE MAXIMUM RATINGS	4
5. RECOMMENDED OPERATING CONDITIONS	5
6. CHARACTERISTICS	6
7. TIMING DIAGRAM EXAMPLE	7
8. STANDARD OPERATING CIRCUIT EXAMPLE	10
9. SPECIFICATION FOR BLEMISH	11
10. CAUTIONS FOR USE	13
11. PACKAGE OUTLINE AND PACKING SPECIFICATION	15

【Note】

The contents of this specification may be changed due to an improvement in characteristics or any other reason. The circuit diagram and others included in this specification are intended for use to explain typical application examples. Therefore, we take no responsibility for any problem as may occur due to the use of the included circuit and for any problem with industrial proprietary rights or other rights.

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1. GENERAL DESCRIPTION

LZ2363B is a 1/3-type(6mm) solid-state image sensor consists of PN photo-diodes and CCDs(charge-coupled devices). Having approximately 470,000 pixels(horizontal 795 x vertical 595), the sensor provides a high resolution stable color image.

Features

- 1) Number of image pixels : Horizontal 752 x vertical 582
Pixel pitch : Horizontal 6.5 μm x vertical 6.3 μm
Number of optical black pixels : Horizontal; front 3 and rear 40
Vertical ; front 11 and rear 2
- 2) Complementary color filter composed of Mg, G, Cy, and Ye
- 3) Low fixed pattern noise and lag
- 4) No burn-in and no image distortion
- 5) Blooming suppression structure
- 6) Built-in output amplifier
- 7) 16-pin half-pitch DIP
(Row space: 11.43 mm)
- 8) Variable electronic shutter(1/50 to 1/10000 s)
- 9) N-type silicon substrate, N-MOS process
- 10) Not designed or rated as radiation hardened
- 11) Compatible with PAL standard

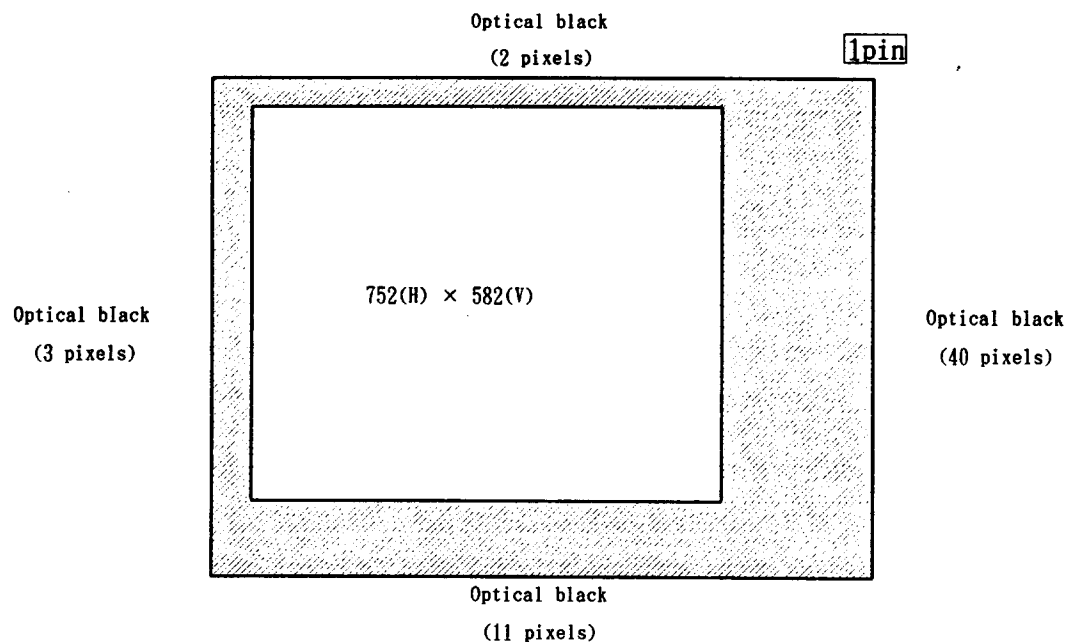
Applications

- 1) Cameras(Cam corders, industrial monitor cameras, etc.)
- 2) Pattern recognition

Others

Combined with the timing IC(LZ95D42/M or LZ95D43/M), SSG IC(LZ95D52 or LZ93N67), V driver IC(LR36683N), and sample/hold IC(IR3P66), this product operates under the performance satisfying these specifications.

2. ARRANGEMENT OF PIXELS AND COLOR FILTERS



(1, 582)

(752, 582)

Cy	Ye	Cy	Ye	Cy
Ng	G	Ng	G	Ng
Cy	Ye	Cy	Ye	Cy
G	Ng	G	Ng	G
Cy	Ye	Cy	Ye	Cy
Ng	G	Ng	G	Ng

Ye	Cy	Ye	Cy	Ye
G	Ng	G	Ng	G
Ye	Cy	Ye	Cy	Ye
Ng	G	Ng	G	Ng
Ye	Cy	Ye	Cy	Ye
G	Ng	G	Ng	G

ODD
field

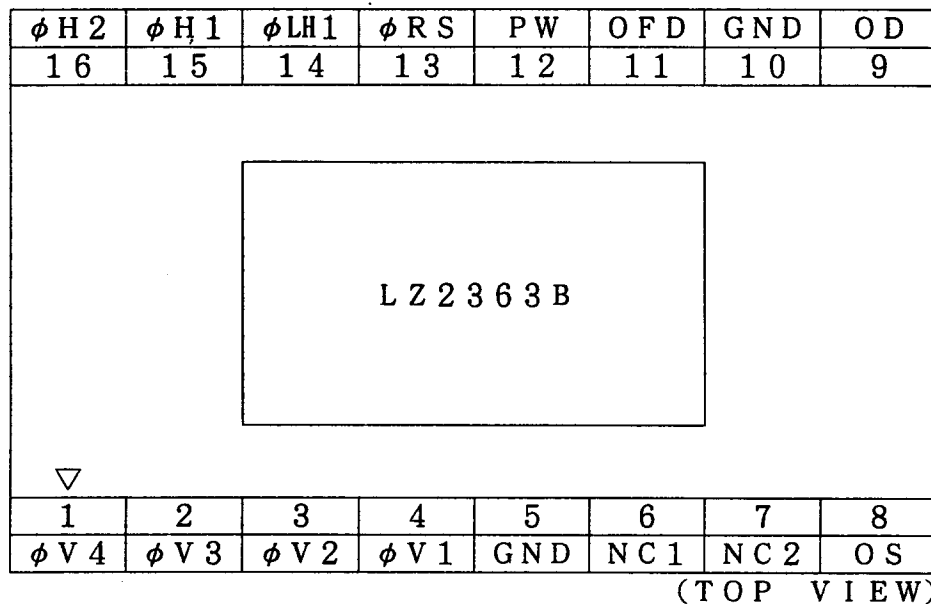
Cy	Ye	Cy	Ye	Cy
Ng	G	Ng	G	Ng
Cy	Ye	Cy	Ye	Cy
G	Ng	G	Ng	G
Cy	Ye	Cy	Ye	Cy
Ng	G	Ng	G	Ng

EVEN
field

Ye	Cy	Ye	Cy	Ye
G	Ng	G	Ng	G
Ye	Cy	Ye	Cy	Ye
Ng	G	Ng	G	Ng
Ye	Cy	Ye	Cy	Ye
G	Ng	G	Ng	G

(1, 1)

(752, 1)

3. PIN IDENTIFICATION

Symbol	Pin name
OD	Output transistor drain
OS	Video output
ϕRS	Reset transistor clock
$\phi V1, \phi V2, \phi V3, \phi V4$	Vertical shift register clock
$\phi H1, \phi H2$	Horizontal shift register clock
$\phi LH1$	Horizontal shift register final stage clock
OFD	Overflow drain
PW	P well
GND	Ground
NC1, NC2	Non connection

4. ABSOLUTE MAXIMUM RATINGS(T_a = 25°C)

Parameter	Symbol	Ratings	Unit
Output transistor drain voltage	V _{OD}	0 ~ +18	V
Reset gate clock voltage	V ϕRS	-0.3 ~ +18	V
Vertical shift register clock voltage	V ϕV	VPW ~ +18	V
Horizontal shift register clock voltage	V ϕH	-0.3 ~ +18	V
Horizontal shift register final stage clock voltage	V ϕLH	-0.3 ~ +18	V
Overflow drain voltage	V _{OFD}	0 ~ +55	V
Voltage difference between Pwell and clock (*Note)	VPW-V ϕ	-28 ~ 0	V
Storage temperature	T _{stg}	-20 ~ +80	°C
Operating ambient temperature	T _{opr}	-20 ~ +70	°C

* Note: The OFD clock ϕ_{OFD} is excluded.

5. RECOMMENDED OPERATING CONDITIONS

Parameter		Symbol	Minimum	Typical	Maximum	Unit
Operating ambient temperature		T _{opr}		25.0		°C
Output transistor drain voltage		V _{OD}	14.5	15.0	16.0	V
Overflow drain voltage	When DC is applied (note1)	V _{OFD}	5.0		19.0	V
	When pulse is applied p-p level (note2)	V ϕ _{OFD}	21.5			V
Ground		GND		0.0		V
P well voltage		V _{PW}	-10.0		V ϕ _{VL}	V
Vertical shift register clock LOW level		V ϕ _{V1L} , V ϕ _{V3L} V ϕ _{V2L} , V ϕ _{V4L}	-9.5	-9.0	-7.5	V
Vertical shift register clock INTERMEDIATE level		V ϕ _{V1I} , V ϕ _{V3I} V ϕ _{V2I} , V ϕ _{V4I}		0.0		V
Vertical shift register clock HIGH level		V ϕ _{V1H} , V ϕ _{V3H}	14.5	15.0	17.0	V
Horizontal shift register clock LOW level		V ϕ _{H1L} , V ϕ _{H2L}	-0.05	0.0	0.05	V
Horizontal shift register clock HIGH level		V ϕ _{H1H} , V ϕ _{H2H}	4.7	5.0	6.0	V
Horizontal shift register final stage clock LOW level		V ϕ _{LH1L}	-0.05	0.0	0.05	V
Horizontal shift register final stage clock HIGH level		V ϕ _{LH1H}	4.7	5.0	6.0	V
Reset gate clock LOW level		V ϕ _{RSL}	0.0		V _{OD} -14.0	V
Reset gate clock HIGH level		V ϕ _{RSH}	V _{OD} -9.5		10.0	V
Vertical shift register clock frequency		f ϕ _{V1} , f ϕ _{V2} f ϕ _{V3} , f ϕ _{V4}		15.63		k Hz
Horizontal shift register clock frequency		f ϕ _{H1} , f ϕ _{H2} f ϕ _{LH1}		14.18		MHz
Reset gate clock frequency		f ϕ _{RS}		14.18		MHz

* Connect NC1 and NC2 to GND directly or through a capacitor larger than 0.047 μ F.

(note1) When DC voltage is applied, shutter speed is 1/50 second.

(note2) When pulse is applied, shutter speed is less than 1/50 second.

6. CHARACTERISTICS (Drive method: Field accumulation)

Ambient temperature: +25°C, but +60°C for parameter No. 4 and 5, 13.

Operating conditions: the typical values specified in recommended conditions.

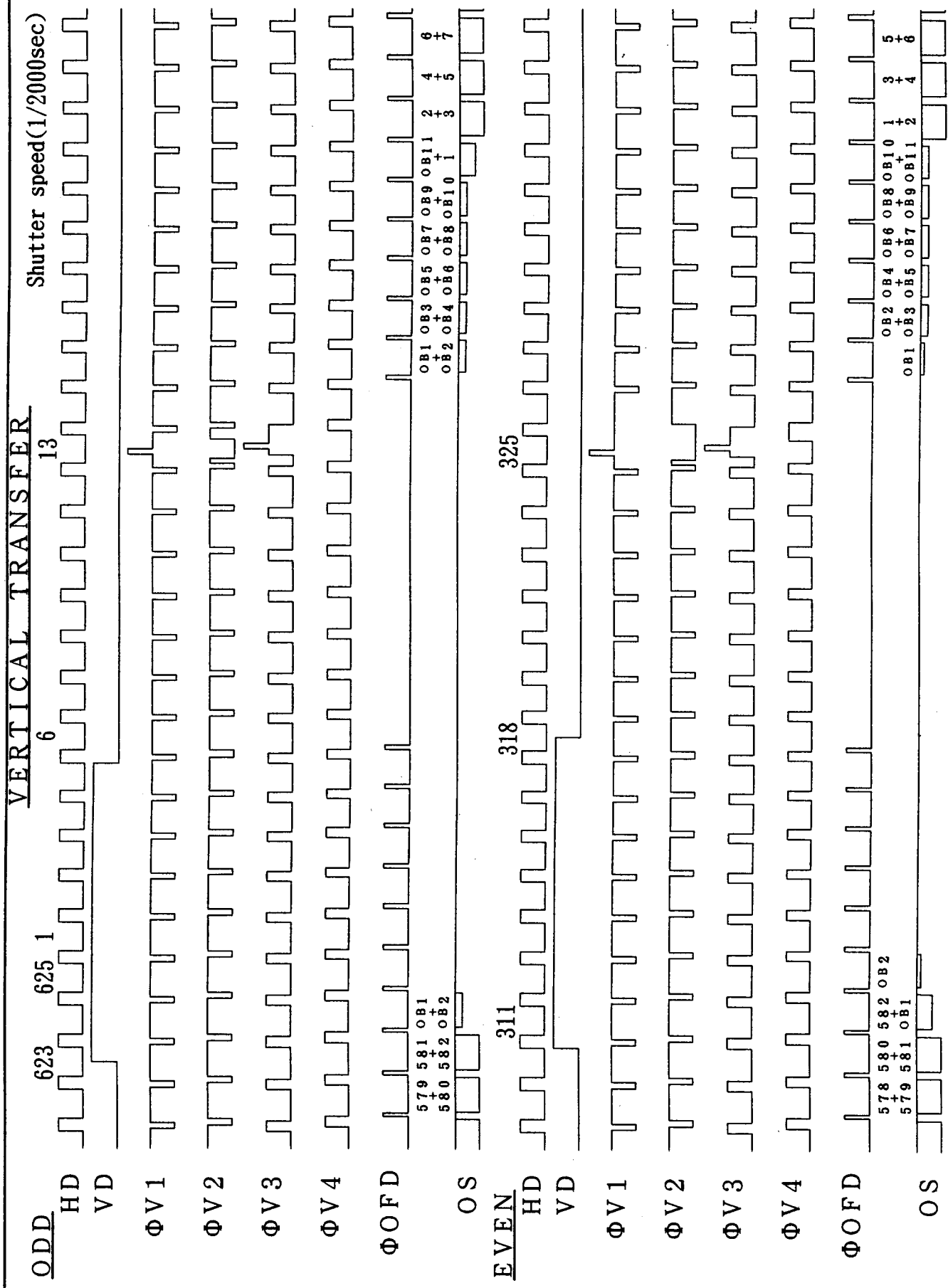
Color Temperature of light source: 3200K / IR cut-off filter(CM-500, 1mm) is used.

No.	Parameter	Symbol	Note	Minimum	Typical	Maximum	Unit
1	Standard output voltage	Vo	(a)		150		mV
2	Photo response non-uniformity	PRNU	(b)			10	%
3	Saturation output voltage	Vsat	(c)	650			mV
4	Dark output voltage	Vdark	(d)		0.5	3.0	mV
5	Dark signal non-uniformity	DSNU	(e)		0.5	2.0	mV
6	Sensitivity	R	(f)	250	330		mV
7	Smear ratio	SMR	(g)		-84	-76	dB
8	Image lag	AI	(h)			1.0	%
9	Blooming suppression ratio	ABL	(i)	500			
10	Current dissipation	IOD			4.0	8.0	mA
11	Output impedance	Ro			350		Ω
12	Dark noise	Vnoise	(j)		0.2	0.3	mV
13	OB difference in level		(k)			1.0	mV
14	Vector breakup		(l)			7.0	°, %
15	Line crawling		(m)			1.5	%
16	Lumminance flicker		(n)			2.0	%

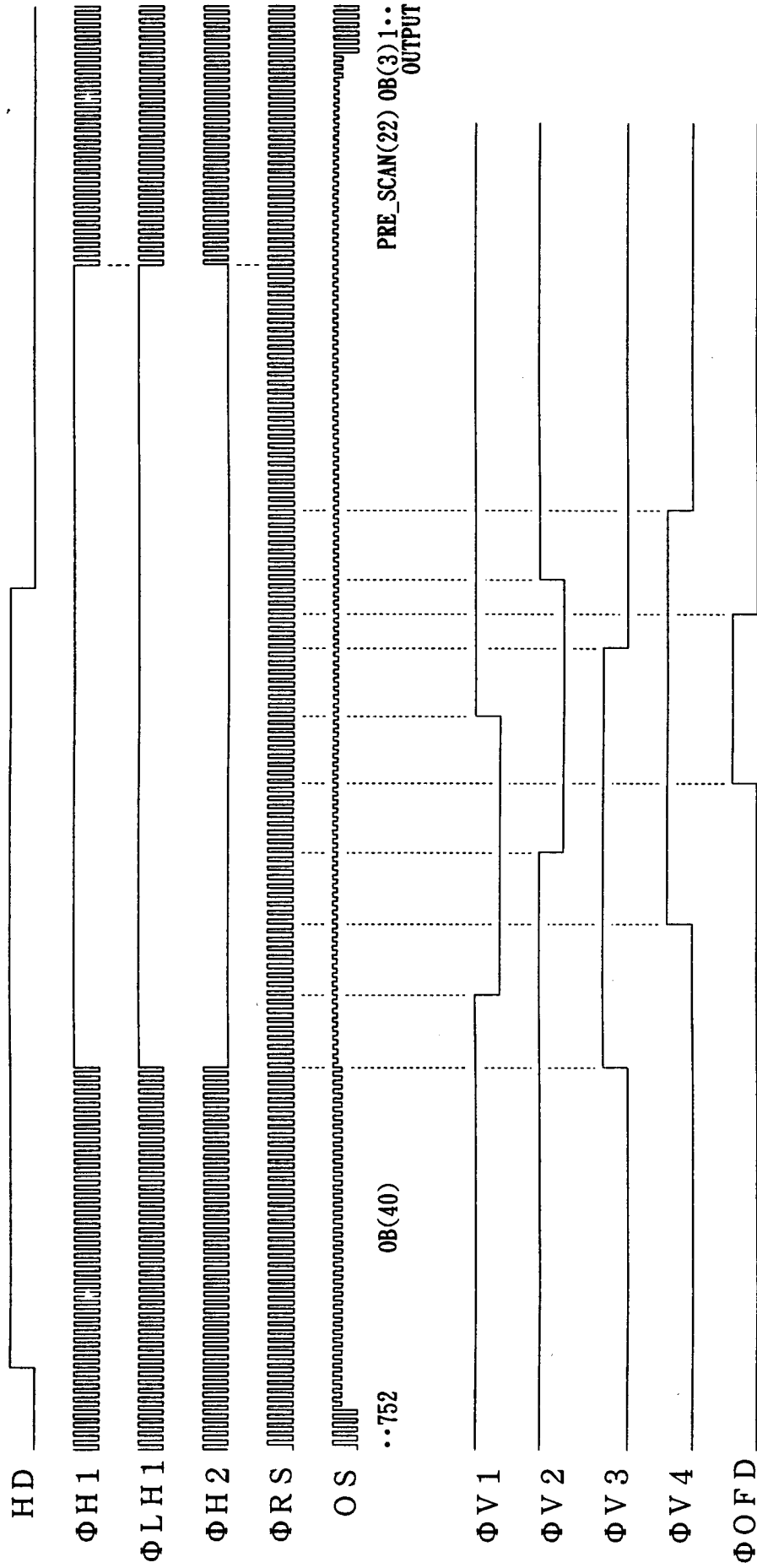
【Note】

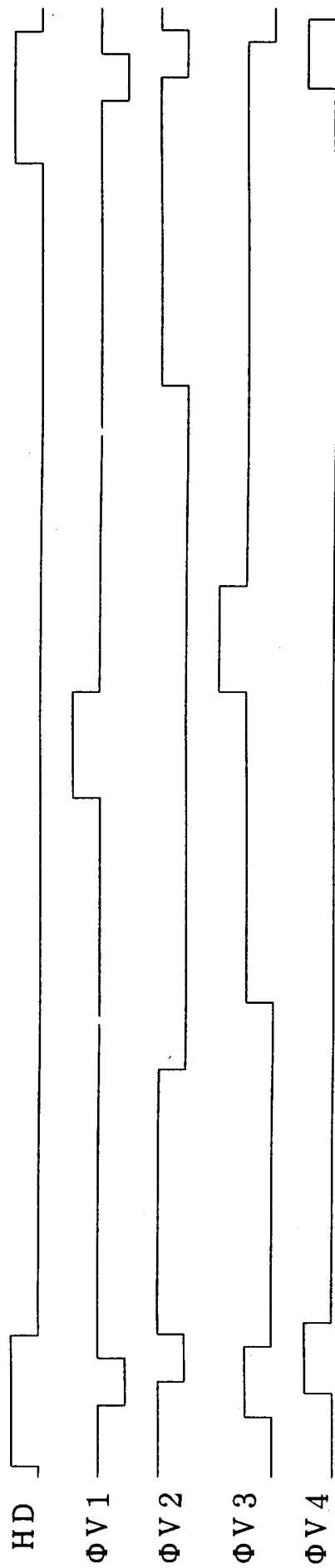
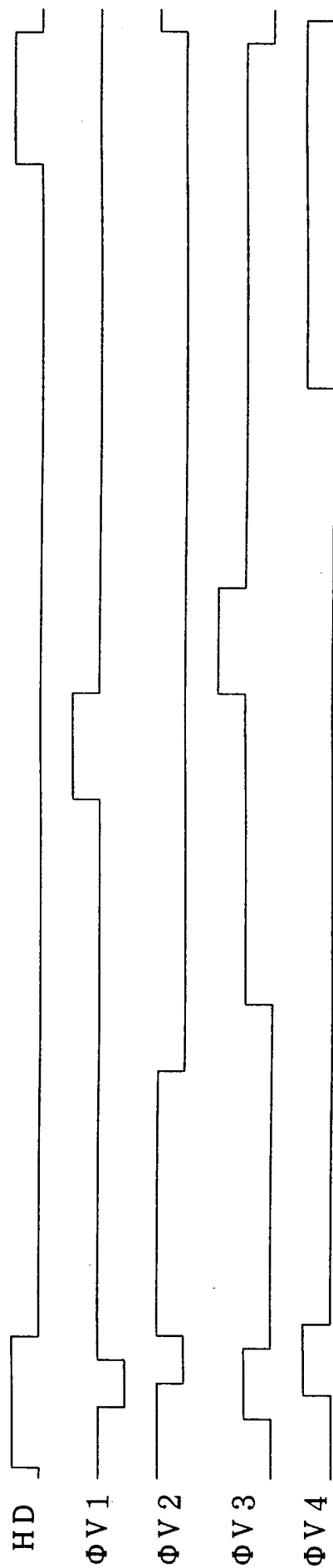
- (a) The average output voltage under the uniform illumination. The standard exposure condition is defined when Vo is 150 mV.
- (b) The image area is divided into 10 × 10 segments under the standard exposure condition. The voltage of a segment is the average output voltage of all pixels within the segment. PRNU is defined by $(V_{\max} - V_{\min}) / V_o$, where V_{\max} and V_{\min} are the maximum and minimum values of each segment's voltage respectively.
- (c) The image area is divided into 10 × 10 segments. The segment's voltage is the average output voltage of all pixels within the segment. Vsat is the minimum segment's voltage under 10 times exposure of the standard exposure condition.
- (d) The average output voltage under the non-exposure condition.
- (e) The image area is divided into 10 × 10 segments under the non-exposure condition. DSNU is defined by $(V_{d\max} - V_{d\min})$, where $V_{d\max}$ and $V_{d\min}$ are the maximum and minimum values of each segment's voltage respectively.
- (f) The average output voltage when a 1000 lux light source with a 90% reflector is imaged by a lens of F4, f50 mm.
- (g) The sensor is exposed only in the central area of V/10 square with a lens at F4, where V is the vertical image size. SMR is defined by the ratio of the output voltage detected during the vertical blanking period to the maximum of the output voltage in the V/10 square.
- (h) The sensor is exposed at the exposure level corresponding to the standard condition. AI is defined by the ratio between the output voltage measured at the 1st field during the non-exposure period and the standard output voltage.
- (i) The sensor is exposed only in the central area of V/10 square, where V is the vertical image size. ABL is the ratio between the exposure at the standard condition and the exposure at a point where a blooming is observed.
- (j) The RMS value of the dark noise (after CDS). (100k ~ 5.0MHz, SC trap on.)
- (k) The difference of the average output voltage between the effective area and the OB area under the non-exposure condition.
- (l) Observe with a vector scope when the color bar chart is imaged under the standard exposure condition.
- (m) The difference of the average output voltage between the (Mg+Cy), (G+Ye) line and the (Mg+Cy), (G+Ye) line under the standard exposure condition.
- (n) The difference of the average output voltage between odd field and even field under the standard exposure condition.

7. TIMING DIAGRAM EXAMPLE

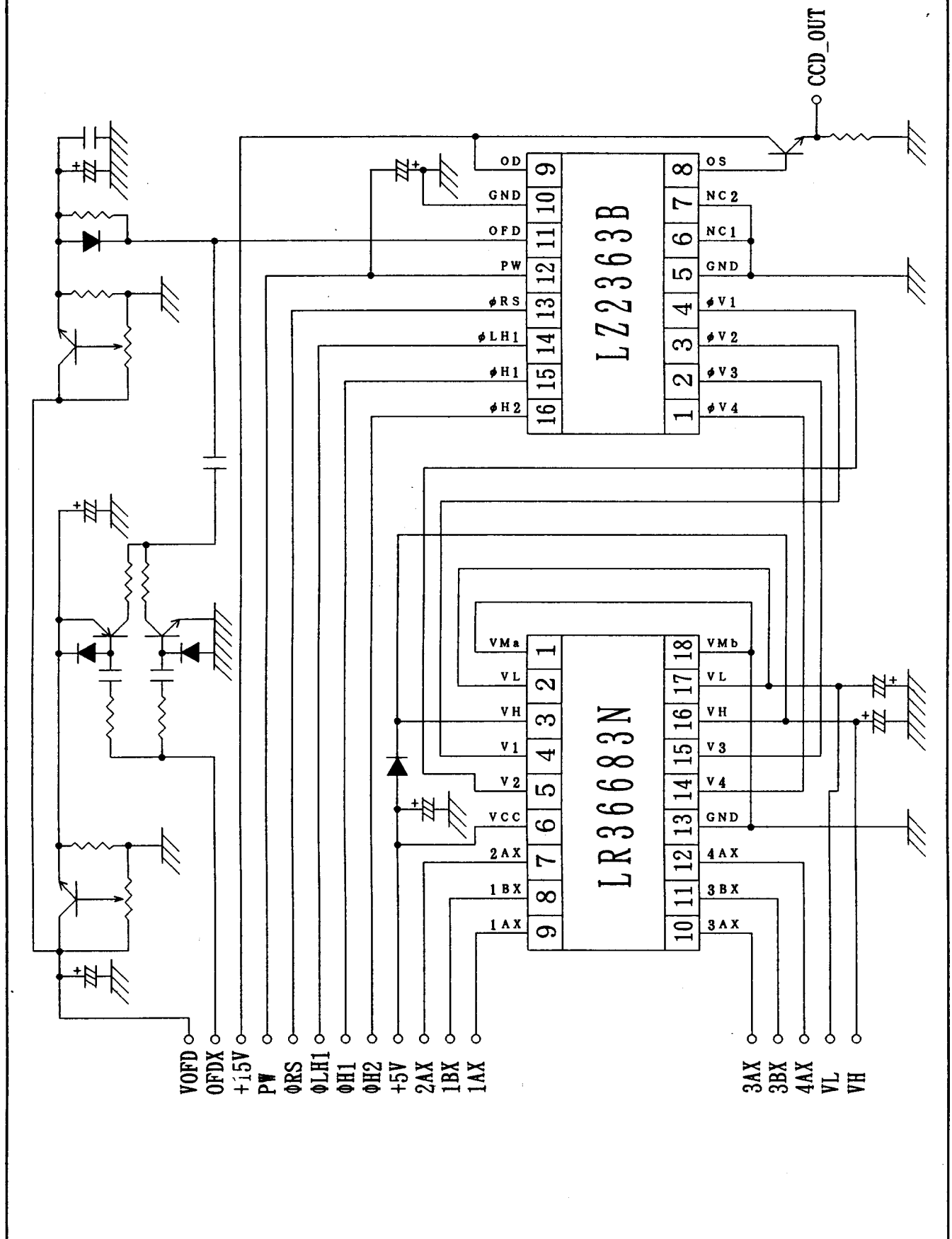


HORIZONTAL TRANSFER



READOUT TIMINGODDEVEN

8. STANDARD OPERATING CIRCUIT EXAMPLE



9. SPECIFICATION FOR BLEMISH

1) Definition of blemish

	Level of blemish (mV)	Permitted number of blemish		Comment
White blemish (Exposed)	$26 \leq B$	0		<ul style="list-style-type: none">• See fig. 9-1(a)、fig. 9-2.• $V_{out} = V_{std}$• $M + N = 10$Up to 4 blemishes are allowed in AREA I
	$18 \leq B < 26$	M		
	$B < 18$	no count		
Black blemish (Exposed)	$26 \leq B$	0		
	$18 \leq B < 26$	N		
	$B < 18$	no count		
White blemish (Non_exposed)		AREA I	AREA II	<ul style="list-style-type: none">• See fig. 9-1(b)、fig. 9-2.• Sum of the blemishes in AREA I and II are allowed up to 6.
	$12 < B$	0	0	
	$9 < B \leq 12$	1	3	
	$7 < B \leq 9$	2	4	
	$6 < B \leq 7$	4	5	
	$B \leq 6$	no count		
White blemish (Shutter mode)	$5.5 \leq B$	0		<ul style="list-style-type: none">• See fig. 9-1(a)、fig. 9-2.• $V_{out} = V_{std}/10$• The electronic shutter speed is set at 1/10000 s
	$B < 5.5$	no count		
Black blemish (Shutter mode)	$5.5 \leq B$	0		
	$B < 5.5$	no count		

(note)

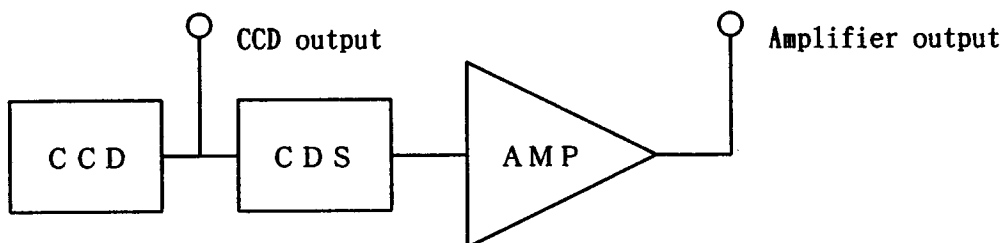
- B : Blemish level defined in fig. 9-1.
- V_{out} : Average output voltage
- V_{std} : 150 mV. The standard output voltage defined in the specification of the characteristics.

2) Definition of stain.

The measuring area is divided into segments which include 20 x 20 pixels, respectively. The difference between the average output voltage of neighboring segments is permitted below 1.5 mV, under the condition that the average output voltage of all imaging pixels is 75 mV ($= V_{std}/2$).

【MEASURING CONDITION】

- $T_a : 60^\circ\text{C}$
- Measuring block diagram



The output voltage is measured at the CCD output.
The gain of the amplifier is adjusted to the unity between the CCD output and the amplifier output.

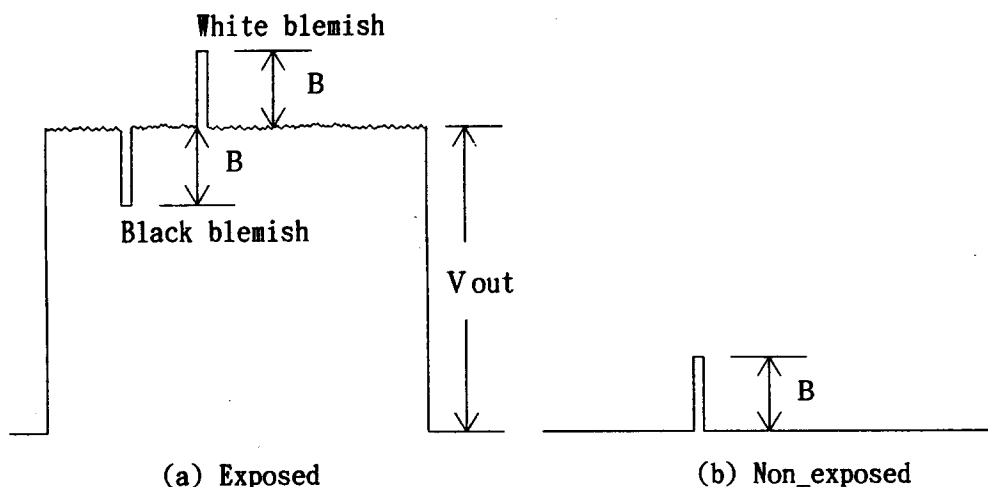


fig. 9-1 Definition of blemish level

(The wave form is the luminance signal measured at the Amplifier output.)

【MEASURING AREA】

Measuring area includes all pixels in the image and the optical black area excluding the outer 10 pixels of the left and right sides and the outer 9 lines of the upper and lower sides in the image area.

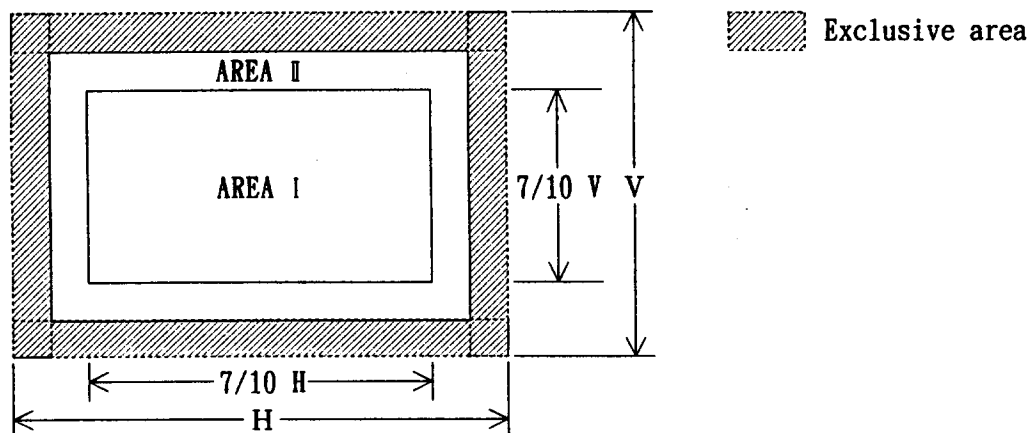


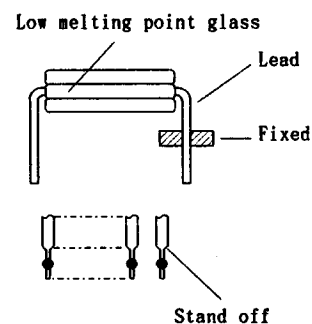
fig. 9-2 Definition of the measuring area

10. CAUTIONS FOR USE

1. Package Breakage

In order to prevent the package from being broken, observe the following instructions:

- 1) The CCD is a precise optical component and the package material is ceramic. Therefore,
 - Take care not to drop the device when mounting, handling, or transporting.
 - Avoid giving a shock to the package. Especially when leads are fixed to the socket and the circuit board, small shock could break the package more easily than when the package isn't fixed.
- 2) When applying force for mounting the device or any other purposes, fix the leads between a joint and a stand_off, so that no stress will be given to the jointed part of the lead. In addition, when applying force, do it at a point below the stand_off part.
 - The leads of the package are fixed with low melting point glass, so stress added to a lead could cause a crack in the low melting point glass in the jointed part of that lead.
- 3) When mounting the package on the housing, be sure that the package is not bent.
 - If a bent package is forced into place between a hard plate or the like, the package may be broken.
- 4) If any damage or breakage occur on the surface of the glass cap, its characteristics could deteriorate. Therefore,
 - Do not hit the glass cap.
 - Do not give a shock large enough to cause distortion.
 - Do not scrub or scratch the glass surface.
 - Even a soft cloth or applicator, if dry, could cause dust to scratch the glass.



2. Electrostatic damage

As compared with general MOS-LSI, CCD has lower ESD.

Therefore, please take the following anti-static measures when handling the CCD:

- 1) Always discharge static electricity by grounding the human body and the instrument to be used. To ground the human body, provide resistance of about 1 Meg ohm between the human body and the ground to be on the safe side.
- 2) When directly handling the device with fingers, hold the part without leads and do not touch any lead.
- 3) To avoid generating static electricity,
 - a. do not scrub the glass surface with cloth or plastic
 - b. do not attach any tape or labels
 - c. do not clean the glass surface with dust-cleaning tape
- 4) When storing or transporting the device, put it in a container of conductive material.

3. Dust and contamination

Dust or contamination on the glass surface could deteriorate the output characteristic or cause a scar. In order to minimize dust or contamination on the glass surface, take the following precautions:

- 1) Handle CCD in a clean environment such as a cleaned booth.
(The cleanliness level should be, if possible, class 1000 at least.)
 - 2) Do not touch the glass surface with fingers. If dust or contamination gets on the glass surface, the following cleaning method is recommended:
 - Dust from static electricity should be blown off with an ionized air blower. For anti-electrostatic measures, however, ground all the leads on the device before blowing off the dust.
 - The contamination on the glass surface should be wiped off with a clean applicator soaked in Isopropyl alcohol. Wipe slowly and gently in one direction only.
- Frequently replace the applicator and do not use the same applicator to clean more than one device.

※ Note: In most cases, dust and contamination are unavoidable, even before the device is first used. It is, therefore, recommended that the above procedures should be taken to wipe out dust and contamination before using the device.

4. Other

- 1) Soldering should be manually performed within 5 seconds at 350°C maximum at soldering iron.
- 2) Do not expose the device to strong light. For the color device, long exposure to strong light will fade the color of the color filters.
- 3) Avoid using or storing the CCD at high temperature or high humidity as it is a precise optical component. Do not give a mechanical shock to the CCD.
- 4) To apply power, first connect GND and then turn on OFD. After turning on OFD, Turn on PW first and then turn on other powers and pulses.
Do not connect the device to or disconnect it from the plug socket while power is being applied.

L Z 2 3 6 3 B

1 1 PACKAGE OUTLINE AND PACKING SPECIFICATION

1. Package Outline Specification

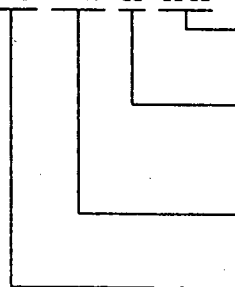
Refer to drawing No. G D G 0 1 6 E - 0 8 E 1.

(The seal resin stick out from the package shall be passed.)

2. Markings

Marking contents

- (1) Product name : L Z 2 3 6 3 B
 (2) Company name : S H A R P
 (3) Country of origin : J A P A N
 (4) Date code : Y Y W W X X X

Denotes the production ref. cord.
(1~2 figures)

Denotes the production day of the week.

1	2	3	4	5	6	7
SUN.	MON.	TUE.	WED.	THU.	FRI.	SAT.

Denotes the production week.

(01, 02, 03,, 52, 53)

Denotes the production year.

(Lower two digits of the year.)

Positions of markings are shown in the package outline drawing(No. GDG016E-08E1).

But, markings shown in that drawing are not provided any measurements of their characters and their positions.

3. Packing Specification

3-1. Packing materials

Material Name	Material Spec.	Purpose
Device case	Paper (100devices/case)	Device packing (2trays/case)
Device tray	Conductive plastic (50devices/tray)	Device fixing
Cover tray	Conductive plastic (1tray/case)	Device covering
Buffer	Cardboard (1sheet/case)	Shock absorber of device tray
Plastic film bag	Plastic film	Device tray fixing
Air cushion	Plastic film	Shock absorber of device case
Tape	Plastic film	Sealing Plastic film bag

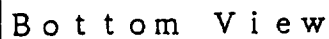
3-2. External appearance of packing

Refer to drawing No. K S E C - 1 0 0 T 2 - 0.

4. Precaution For Unpacking

- 1) Before unpacking, confirm the imports of the chapter "Handling Precaution" in this device specifications.
 2) Unpacking should be done on the stand treated with anti-ESD. At that time, the same anti-ESD treatment should be done to operator's body, too.

ISSUE DATE	9 4 . 1 2 . 0 2	A. Senku Y. Taheda G. Seko	(NOTE)
ISSUE NUMBER	4 C 0 2 2 5 D C		
S/C NUMBER	L Z 2 3 6 3 B		



尺 度 SCALE		単 位 UNIT		△ . .					
/		1 = 1 / 1 mm		△ . .					
材質 MATERIAL		仕 上 FINISH		改訂日 DATE		改訂記事 REVISE		担当 CHARGE	
				名 称 NAME		DMPG16E			
				コード CODE					
シャープ株式会社 IC Group				図 番 DRAWING No.		GDG016E-08E1			
ASSEMBLY ENGINEERING DEPT. SHARP CORPORATION									

LZ2363B

